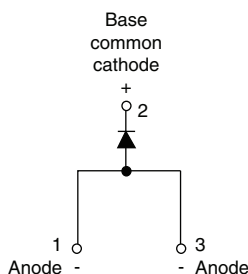


Surface Mountable Fast Soft Recovery Rectifier Diode, 20 A


D²PAK (SMD-220)


FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Designed and qualified according to JEDEC-JESD47
- Compliant to RoHS Directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Output rectification and freewheeling in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

DESCRIPTION

The VS-20ETF..SPbF soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRODUCT SUMMARY

Package	TO-263AB (D ² PAK)
$I_{F(AV)}$	20 A
V_R	200 V, 400 V, 600 V
V_F at I_F	1.3 V
I_{FSM}	300 A
t_{rr}	60 ns
T_J max.	150 °C
Diode variation	Single die
Snap factor	0.6

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	20	A
V_{RRM}		200 to 600	V
I_{FSM}		300	A
V_F	10 A, $T_J = 25$ °C	1.2	V
t_{rr}	1 A, 100 A/ μ s	60	ns
T_J	Range	- 40 to 150	°C

VOLTAGE RATINGS

PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
VS-20ETF02SPbF	200	300	5
VS-20ETF04SPbF	400	500	
VS-20ETF06SPbF	600	700	

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 97$ °C, 180° conduction half sine wave	20	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	250	
		10 ms sine pulse, no voltage reapplied	300	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	316	A ² s
		10 ms sine pulse, no voltage reapplied	442	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	4420	A ² $\sqrt{s}$

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	20 A, $T_J = 25\text{ }^{\circ}\text{C}$		1.30	V
		60 A, $T_J = 25\text{ }^{\circ}\text{C}$		1.67	
Forward slope resistance	r_t			12.5	m Ω
Threshold voltage	$V_{F(TO)}$	$T_J = 150\text{ }^{\circ}\text{C}$		0.9	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{Rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$		5.0	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Reverse recovery time	t_{rr}	I_F at 20 Apk 100 A/ μ s 25 $^{\circ}\text{C}$	160	ns	
Reverse recovery current	I_{rr}		10	A	
Reverse recovery charge	Q_{rr}		1.25	μ C	
Snap factor	S	Typical	0.6		

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		- 40 to 150	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	0.9	$^{\circ}\text{C/W}$
Maximum thermal resistance junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		40	
Soldering temperature	T_S		240	$^{\circ}\text{C}$
Approximate weight			2	g
			0.07	oz.
Marking device		Case style TO-263AB (D ² PAK)	20ETF02S	
			20ETF04S	
			20ETF06S	

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μ m) copper 40 $^{\circ}\text{C/W}$.
For recommended footprint and soldering techniques refer to application note #AN-994.

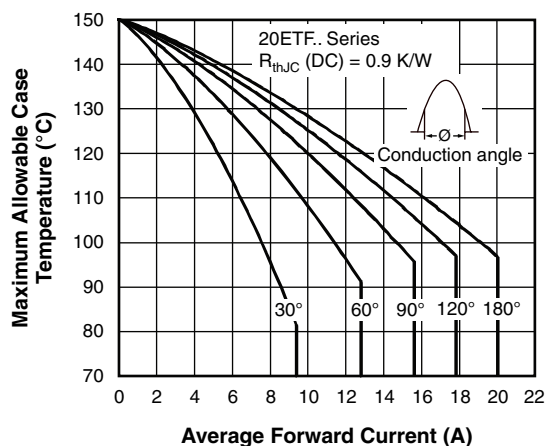


Fig. 1 - Current Rating Characteristics

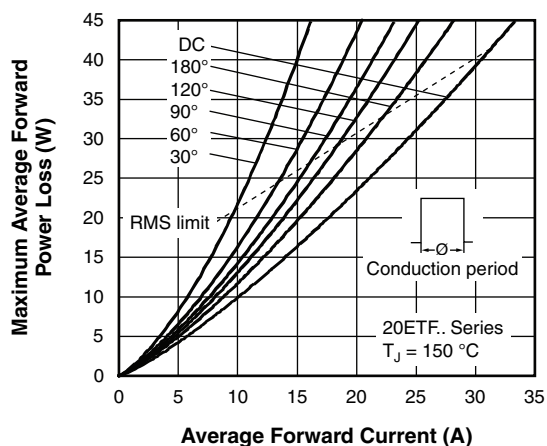


Fig. 4 - Forward Power Loss Characteristics

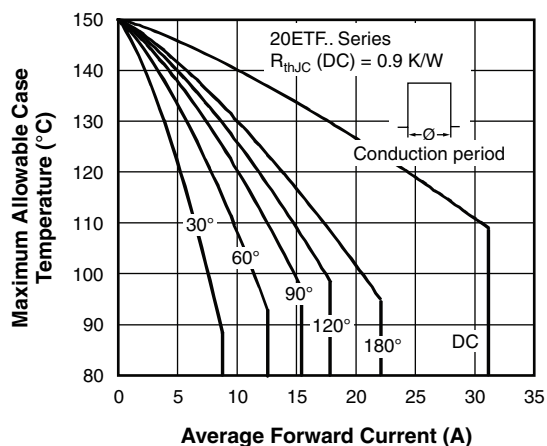


Fig. 2 - Current Rating Characteristics

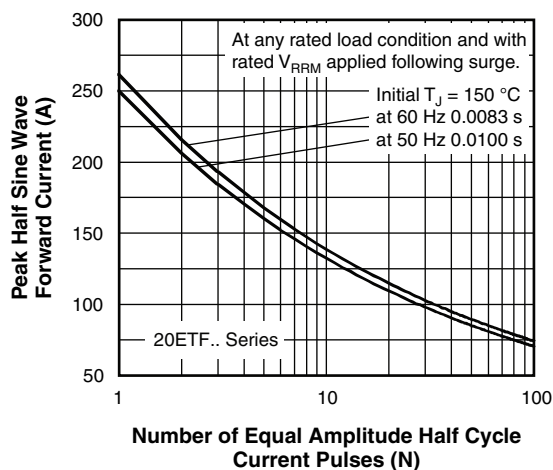


Fig. 5 - Maximum Non-Repetitive Surge Current

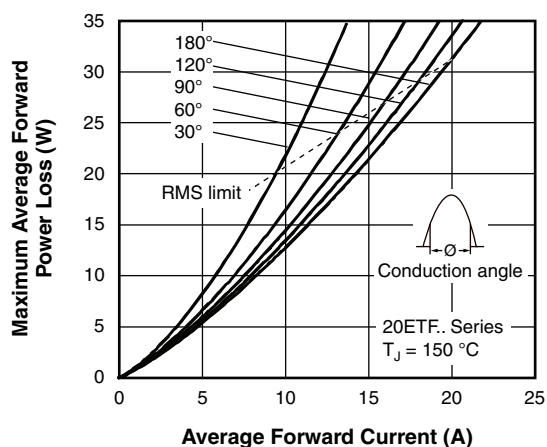


Fig. 3 - Forward Power Loss Characteristics

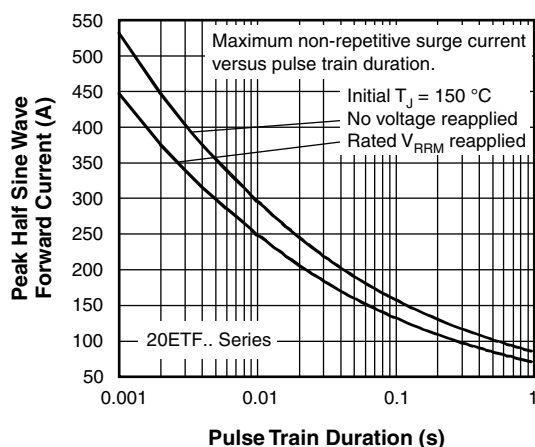


Fig. 6 - Maximum Non-Repetitive Surge Current

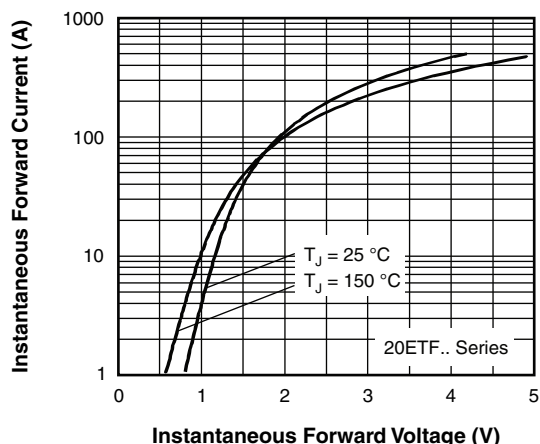


Fig. 7 - Forward Voltage Drop Characteristics

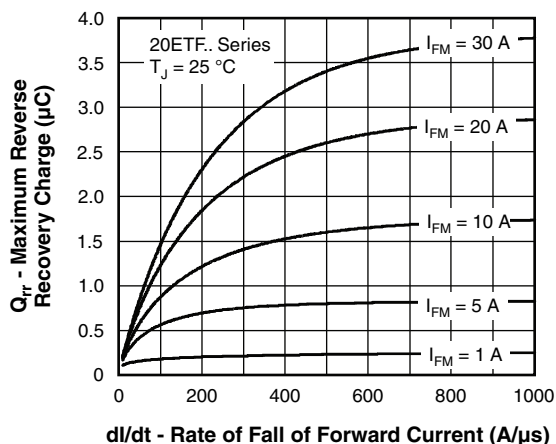


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ °C}$

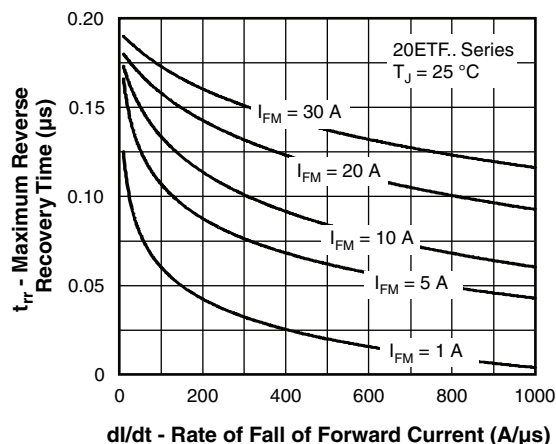


Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ °C}$

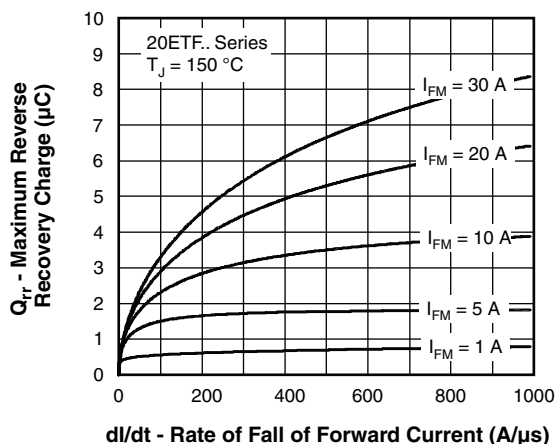


Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ °C}$

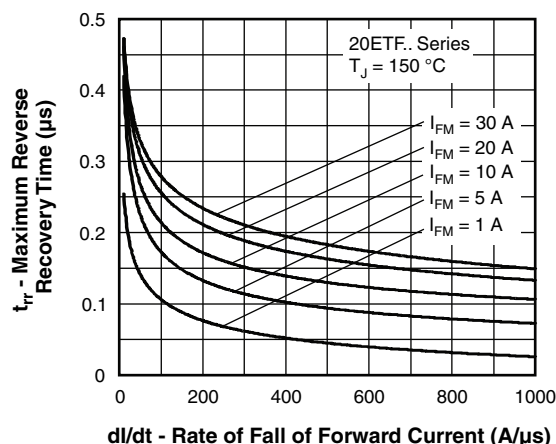


Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ °C}$

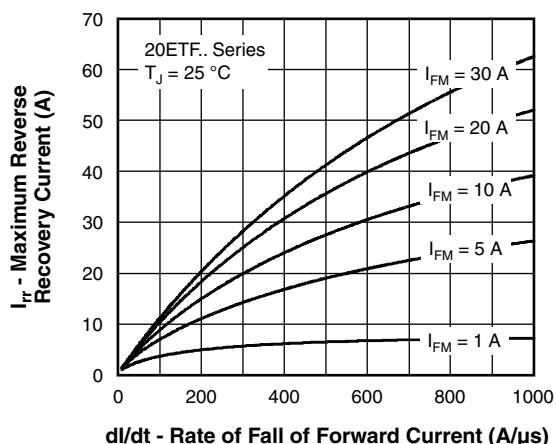
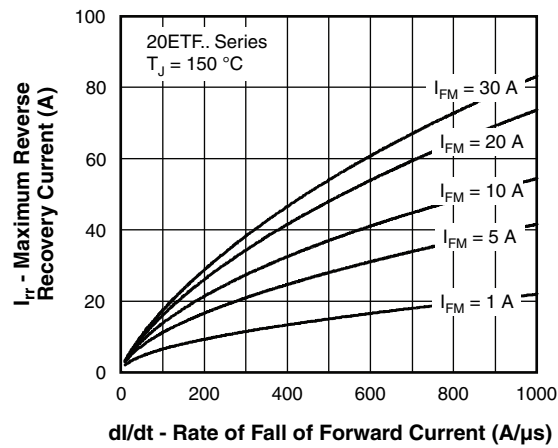
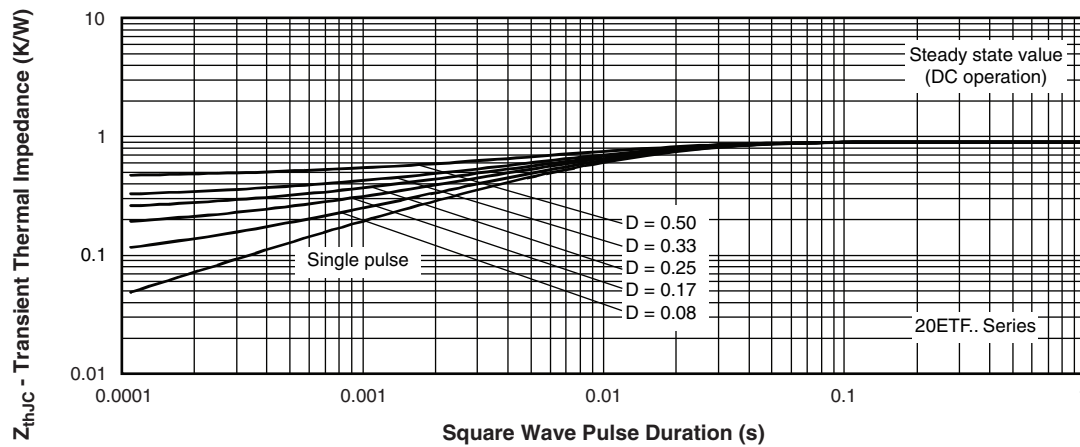


Fig. 12 - Recovery Current Characteristics, $T_J = 25\text{ °C}$


Fig. 13 - Recovery Current Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

Fig. 14 - Thermal Impedance Z_{thJC} Characteristics



ORDERING INFORMATION TABLE

Device code	VS-	20	E	T	F	06	S	TRL	PbF
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating (20 = 20 A)
- 3** - Circuit configuration:
E = Single diode
- 4** - Package:
T = TO-220
- 5** - Type of silicon:
F = Fast soft recovery rectifier
- 6** - Voltage code x 100 = V_{RRM}
- 7** - S = D²PAK
- 8** -
 - None = Tube
 - TRR = Tape and reel (right oriented)
 - TRL = Tape and reel (left oriented)
- 9** - PbF = Lead (Pb)-free

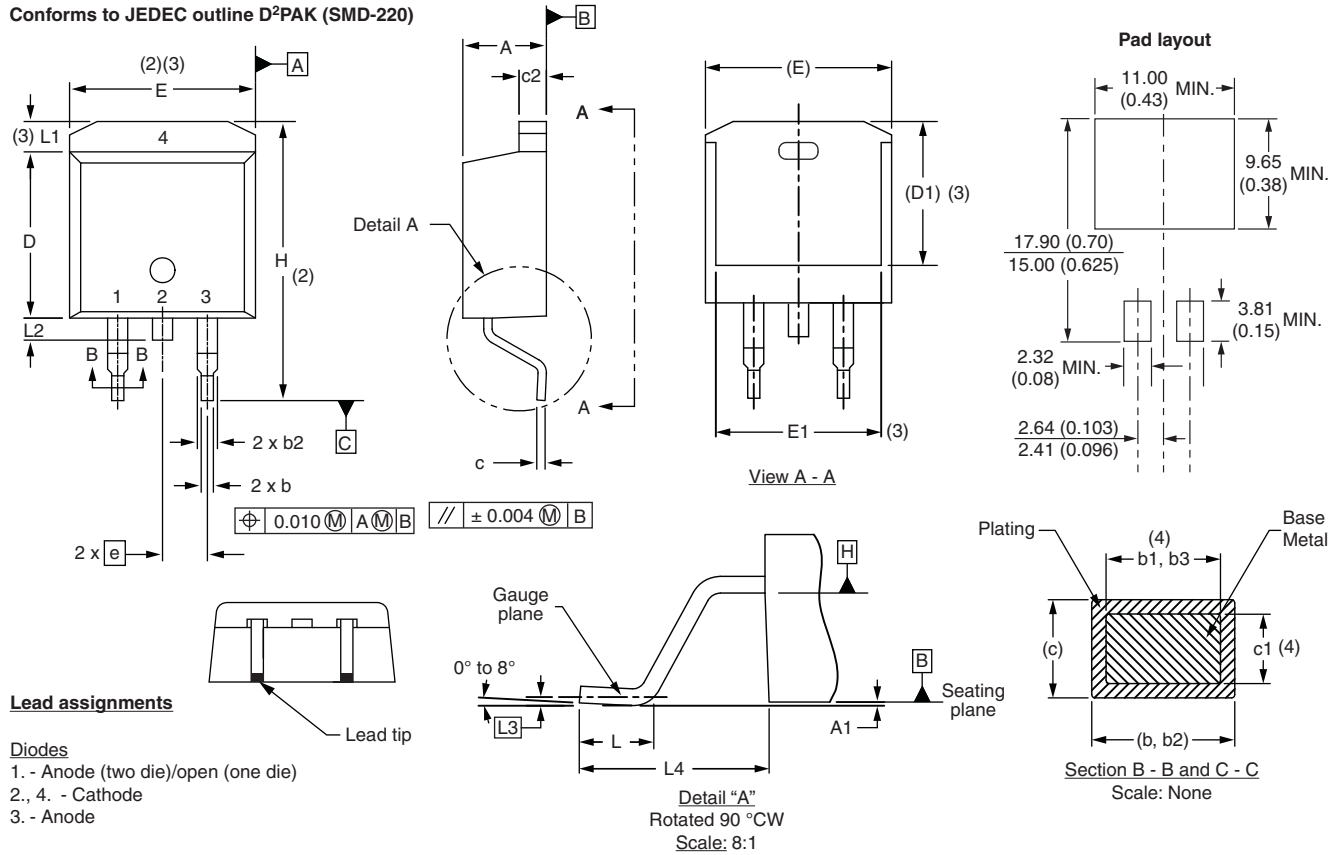
02 = 200 V
04 = 400 V
06 = 600 V

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC outline TO-263AB



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